LM1036 Dual DC Operated Tone/Volume/Balance Circuit

Check for Samples: LM1036

FEATURES

- **Wide supply voltage range, 9V to 16V**
- **Large volume control range, 75 dB typical**
- **Tone control, ±15 dB typical**
- **Channel separation, 75 dB typical**
- **Low distortion, 0.06% typical for an input level of 0.3 Vrms**
- **High signal to noise, 80 dB typical for an input level of 0.3 Vrms**
- **Few external components required**

DESCRIPTION

The LM1036 is a DC controlled tone (bass/treble), volume and balance circuit for stereo applications in car radio, TV and audio systems. An additional control input allows loudness compensation to be simply effected.

Four control inputs provide control of the bass, treble, balance and volume functions through application of DC voltages from a remote control system or, alternatively, from four potentiometers which may be biased from a zener regulated supply provided on the circuit.

Each tone response is defined by a single capacitor chosen to give the desired characteristic.

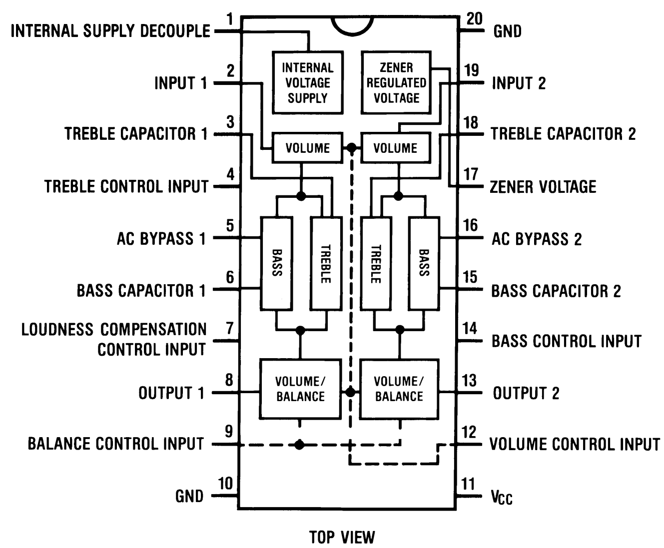

Figure 1. Dual-In-Line (DIP) and Small Outline (SO) Package

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

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Absolute Maximum Ratings [1]

Supply Voltage	16V
Control Pin Voltage (Pins 4, 7, 9, 12, 14)	V_{CC}
Operating Temperature Range	0°C to +70°C
Storage Temperature Range	−65°C to +150°C
Power Dissipation	1W
Lead Temp. (Soldering, 10 seconds)	260°C

(1) “Absolute Maximum Ratings” indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits.

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Electrical Characteristics

V_{CC}=12V, T_A=25°C (unless otherwise stated)

Parameter	Conditions	Min	Typ	Max	Units
Supply Voltage Range	Pin 11	9		16	V
Supply Current			35	45	mA
Zener Regulated Output	Pin 17				
Voltage			5.4		V
Current				5	mA
Maximum Output Voltage	Pins 8, 13; f=1 kHz				
	V_{CC}=9V, Maximum Gain		0.8		Vrms
	V_{CC}=12V	0.8	1.0		Vrms
Maximum Input Voltage	Pins 2, 19; f=1 kHz, V_{CC} 2V	1.3	1.6		Vrms
	Gain=−10 dB				
Input Resistance	Pins 2, 19; f=1 kHz	20	30		kΩ
Output Resistance	Pins 8, 13; f=1 kHz		20		Ω
Maximum Gain	V(Pin 12)=V(Pin 17); f=1 kHz	−2	0	2	dB
Volume Control Range	f=1 kHz	70	75		dB
Gain Tracking	f=1 kHz				
Channel 1–Channel 2	0 dB through −40 dB		1	3	dB
	−40 dB through −60 dB		2		dB
Balance Control Range	Pins 8, 13; f=1 kHz		1		dB
			−26	−20	dB
Bass Control Range	f=40 Hz, C_b=0.39 μF				
(1)	V(Pin 14)=V(Pin 17)	12	15	18	dB
	V(Pin 14)=0V	−12	−15	−18	dB
Treble Control Range	f= 16 kHz, C_t,=0.01 μF				
(1)	V(Pin 4)=V(Pin 17)	12	15	18	dB
	V(Pin 4)=0V	−12	−15	−18	dB
Total Harmonic Distortion	f=1 kHz, V_{IN}=0.3 Vrms				
	Gain=0 dB		0.06	0.3	%
	Gain=−30 dB		0.03		%
Channel Separation	f=1 kHz, Maximum Gain	60	75		dB
Signal/Noise Ratio	Unweighted 100 Hz–20 kHz		80		dB
	Maximum Gain, 0 dB=0.3 Vrms				
	CCIR/ARM (2)				
	Gain=0 dB, V_{IN}=0.3 Vrms	75	79		dB
	Gain=−20 dB, V_{IN}=1.0 Vrms		72		dB
Output Noise Voltage at	CCIR/ARM (2)		10	16	μV
Minimum Gain					
Supply Ripple Rejection	200 mVrms, 1 kHz Ripple	35	50		dB
Control Input Currents	Pins 4, 7, 9, 12, 14 (V=0V)		−0.6	−2.5	μA
Frequency Response	−1 dB (Flat Response		250		kHz
	20 Hz–16 kHz)				

(1) The tone control range is defined by capacitors C_b and C_t. See Application Notes.
(2) Gaussian noise, measured over a period of 50 ms per channel, with a CCIR filter referenced to 2 kHz and an average-responding meter.

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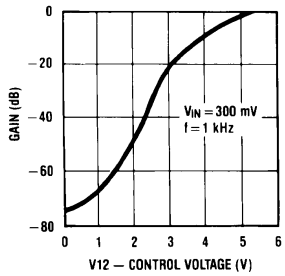
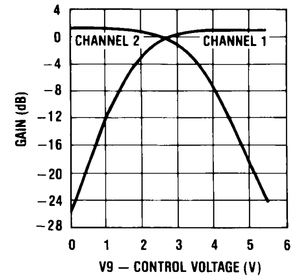
Typical Performance Characteristics

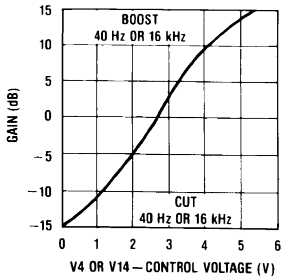
Volume Control Characteristics



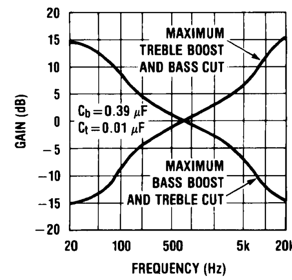
Balance Control Characteristic



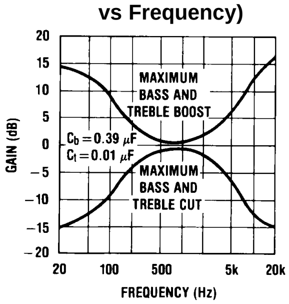
Tone Control Characteristic



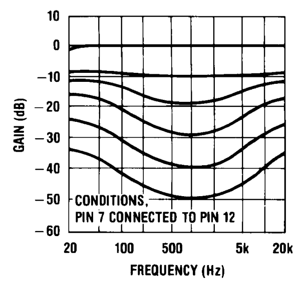
Tone Characteristic (Gain vs Frequency)



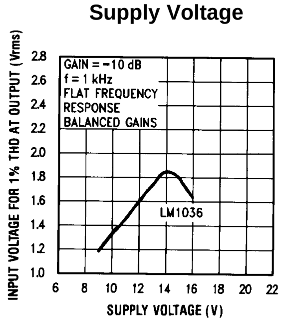
Tone Characteristic (Gain vs Frequency)



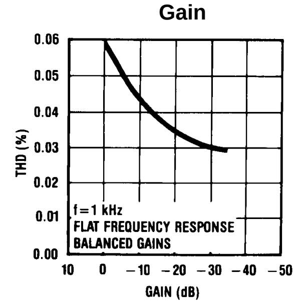
Loudness Compensated Volume Characteristic



Input Signal Handling vs Supply Voltage



THD vs Gain



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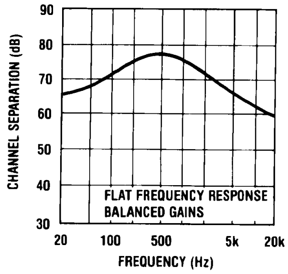
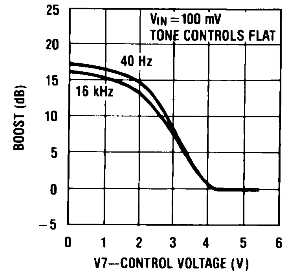
Typical Performance Characteristics (continued)

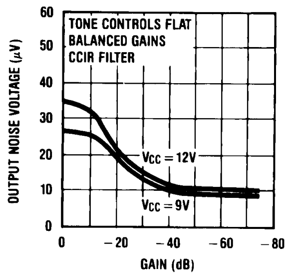
Channel Separation vs Frequency



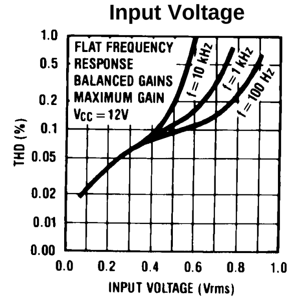
Loudness Control Characteristic



Output Noise Voltage vs Gain



THD vs Input Voltage



Application Notes

TONE RESPONSE

The maximum boost and cut can be optimized for individual applications by selection of the appropriate values of C_t (treble) and C_b (bass).

The tone responses are defined by the relationships:

$$\text{Bass Response} = \frac{1 + \frac{0.00065\,(1 - a_b)}{j\omega C_b}}{1 + \frac{0.00065 a_b}{j\omega C_b}}$$

$$\text{Treble Response} = \frac{1 + j\omega 5500(1 - a_t)C_t}{1 + j\omega 5500 a_t C_t} \quad (1)$$

Where a_b=a_t=0 for maximum bass and treble boost respectively and a_b=a_t=1 for maximum cut.

For the values of C_b and C_t of 0.39 μF and 0.01 μF as shown in the Application Circuit, 15 dB of boost or cut is obtained at 40 Hz and 16 kHz.

ZENER VOLTAGE

A zener voltage (pin 17=5.4V) is provided which may be used to bias the control potentiometers. Setting a DC level of one half of the zener voltage on the control inputs, pins 4, 9, and 14, results in the balanced gain and flat response condition. Typical spread on the zener voltage is ±100 mV and this must be taken into account if control signals are used which are not referenced to the zener voltage. If this is the case, then they will need to be derived with similar accuracy.

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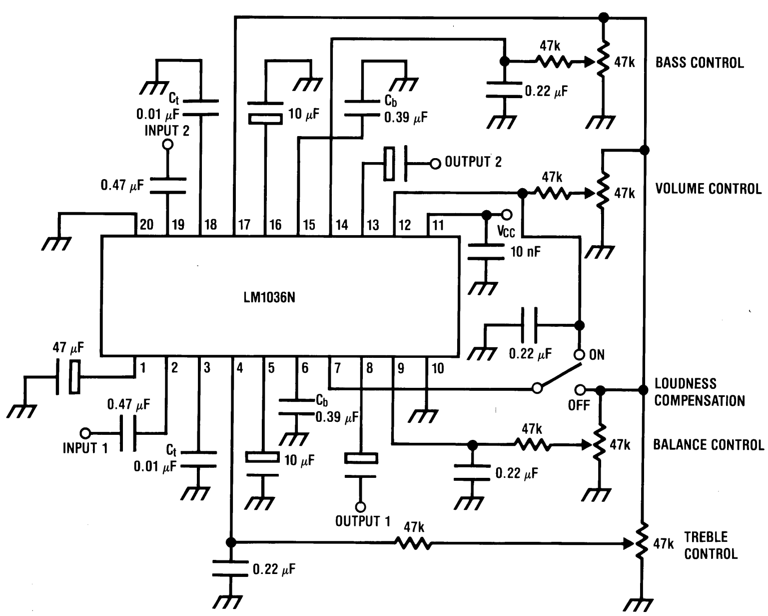
LOUDNESS COMPENSATION

A simple loudness compensation may be effected by applying a DC control voltage to pin 7. This operates on the tone control stages to produce an additional boost limited by the maximum boost defined by C_b and C_t. There is no loudness compensation when pin 7 is connected to pin 17. Pin 7 can be connected to pin 12 to give the loudness compensated volume characteristic as illustrated without the addition of further external components. (Tone settings are for flat response, C_b and C_t as given in Application Circuit.) Modification to the loudness characteristic is possible by changing the capacitors C_b and C_t for a different basic response or, by a resistor network between pins 7 and 12 for a different threshold and slope.

SIGNAL HANDLING

The volume control function of the LM1036 is carried out in two stages, controlled by the DC voltage on pin 12, to improve signal handling capability and provide a reduction of output noise level at reduced gain. The first stage is before the tone control processing and provides an initial 15 dB of gain reduction, so ensuring that the tone sections are not overdriven by large input levels when operating with a low volume setting. Any combination of tone and volume settings may be used provided the output level does not exceed 1 Vrms, V_{CC}=12V (0.8 Vrms, V_{CC}=9V). At reduced gain (<−6 dB)the input stage will overload if the input level exceeds 1.6 Vrms, V_{CC}=12V(1.1 Vrms, V_{CC}=9V). As there is volume control on the input stages, the inputs may be operated with a lower overload margin than would otherwise be acceptable, allowing a possible improvement in signal to noise ratio.

Application Circuit



Applications Information

OBTAINING MODIFIED RESPONSE CURVES

The LM1036 is a dual DC controlled bass, treble, balance and volume integrated circuit ideal for stereo audio systems.

In the various applications where the LM1036 can be used, there may be requirements for responses different to those of the standard application circuit given in the data sheet. This application section details some of the simple variations possible on the standard responses, to assist the choice of optimum characteristics for particular applications.

TONE CONTROLS

Summarizing the relationship given in the data sheet, basically for an increase in the treble control range C_t must be increased, and for increased bass range C_b must be reduced.

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Figure 2 shows the typical tone response obtained in the standard application circuit. (C_t=0.01 µF, C_b=0.39 µF). Response curves are given for various amounts of boost and cut.

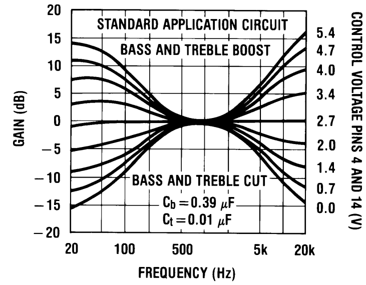

Figure 2. Tone Characteristic (Gain vs Frequency)

Figure 3 and Figure 4 show the effect of changing the response defining capacitors C_t and C_b to 2Ct, C_b/2 and 4C_t, C_b/4 respectively, giving increased tone control ranges. The values of the bypass capacitors may become significant and affect the lower frequencies in the bass response curves.

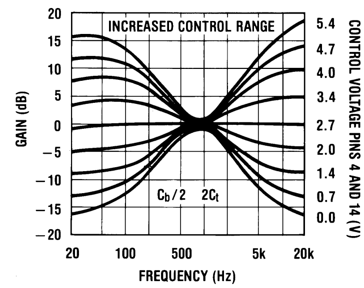

Figure 3. Tone Characteristic (Gain vs Frequency)

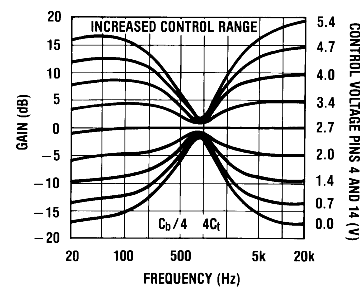

Figure 4. Tone Characteristic (Gain vs Frequency)

Figure 5 shows the effect of changing C_t and C_b in the opposite direction to C_t/2, 2C_b respectively giving reduced control ranges. The various results corresponding to the different C_t and C_b values may be mixed if it is required to give a particular emphasis to, for example, the bass control. The particular case with C_b/2, C_t is illustrated in Figure 6.

Restriction of Tone Control Action at High or Low Frequencies

It may be desired in some applications to level off the tone responses above or below certain frequencies for example to reduce high frequence noise.

This may be achieved for the treble response by including a resistor in series with C_t. The treble boost and cut will be 3 dB less than the standard circuit when R=X_C.

A similar effect may be obtained for the bass response by reducing the value of the AC bypass capacitors on pins 5 (channel 1) and 16 (channel 2). The internal resistance at these pins is 1.3 kΩ and the bass boost/cut will be approximately 3 dB less with X_C at this value. An example of such modified response curves is shown in Figure 7. The input coupling capacitors may also modify the low frequency response.

It will be seen from Figure 3 and Figure 4 that modifying C_t and C_b for greater control range also has the effect of flattening the tone control extremes and this may be utilized, with or without additional modification as outlined above, for the most suitable tone control range and response shape.

Other Advantages of DC Controls

The DC controls make the addition of other features easy to arrange. For example, the negative-going peaks of the output amplifiers may be detected below a certain level, and used to bias back the bass control from a high boost condition, to prevent overloading the speaker with low frequency components.

LOUDNESS CONTROL

The loudness control is achieved through control of the tone sections by the voltage applied to pin 7; therefore, the tone and loudness functions are not independent. There is normally 1 dB more bass than treble boost (40 Hz–16 kHz) with loudness control in the standard circuit. If a greater difference is desired, it is necessary to introduce an offset by means of C_t or C_b or by changing the nominal control voltage ranges.

Figure 8 shows the typical loudness curves obtained in the standard application circuit at various volume levels (C_b=0.39 μF).

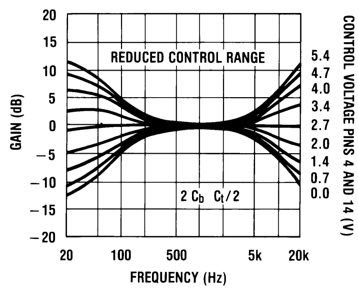

Figure 5. Tone Characteristic (Gain vs Frequency)

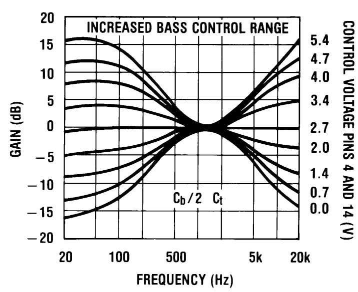

Figure 6. Tone Characteristic (Gain vs Frequency)

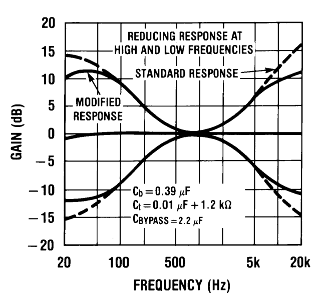

Figure 7. Tone Characteristic (Gain vs Frequency)

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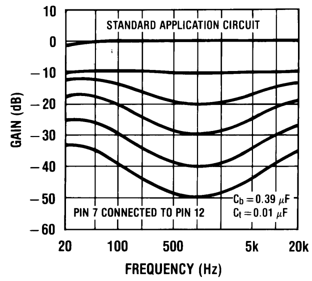

Figure 8. Loudness Compensated Volume Characteristic

Figure 9 and Figure 10 illustrate the loudness characteristics obtained with C_b changed to $C_b/2$ and $C_b/4$ respectively, C_t being kept at the nominal 0.01 μF. These values naturally modify the bass tone response as in Figure 3 and Figure 4.

With pins 7 (loudness) and 12 (volume) directly connected, loudness control starts at typically −8 dB volume, with most of the control action complete by −30 dB.

Figure 11 and Figure 12 show the effect of resistively offsetting the voltage applied to pin 7 towards the control reference voltage (pin 17). Because the control inputs are high impedance, this is easily done and high value resistors may be used for minimal additional loading. It is possible to reduce the rate of onset of control to extend the active range to −50 dB volume control and below.

The control on pin 7 may also be divided down towards ground bringing the control action on earlier. This is illustrated in Figure 13, With a suitable level shifting network between pins 12 and 7, the onset of loudness control and its rate of change may be readily modified.

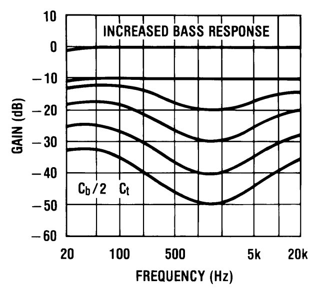

Figure 9. Loudness Compensated Volume Characteristic

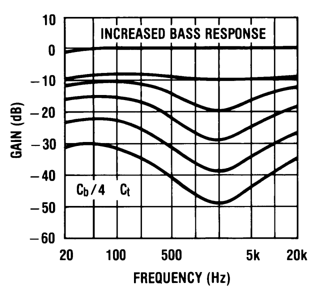

Figure 10. Loudness Compensated Volume Characteristic

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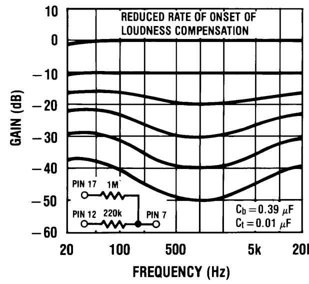

Figure 11. Loudness Compensated Volume Characteristic

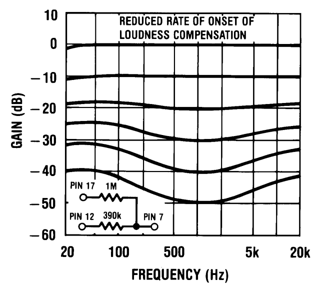

Figure 12. Loudness Compensated Volume Characteristic

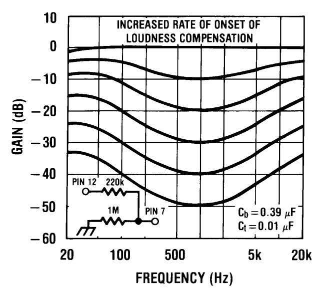

Figure 13. Loudness Compensated Volume Characteristic

When adjusted for maximum boost in the usual application circuit, the LM1036 cannot give additional boost from the loudness control with reducing gain. If it is required, some additional boost can be obtained by restricting the tone control range and modifying C_t, C_b, to compensate. A circuit illustrating this for the case of bass boost is shown in Figure 13. The resulting responses are given in Figure 15 showing the continuing loudness control action possible with bass boost previously applied.

USE OF THE LM1036 ABOVE AUDIO FREQUENCIES

The LM1036 has a basic response typically 1 dB down at 250 kHz (tone controls flat) and therefore by scaling C_b and C_t, it is possible to arrange for operation over a wide frequency range for possible use in wide band equalization applications. As an example Figure 16 shows the responses obtained centered on 10 kHz with C_b=0.039 µF and C_t=0.001 µF.

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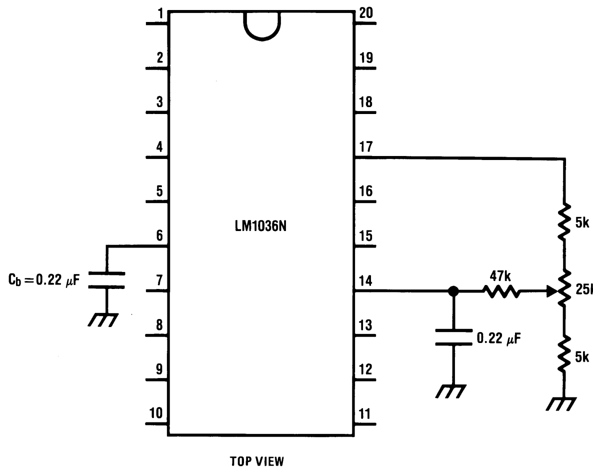


Figure 14. Modified Application Circuit for Additional Bass Boost with Loudness Control

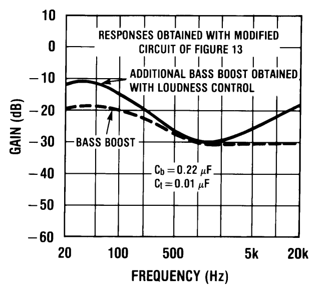


Figure 15. Loudness Compensated Volume Characteristic

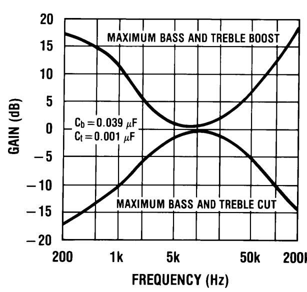
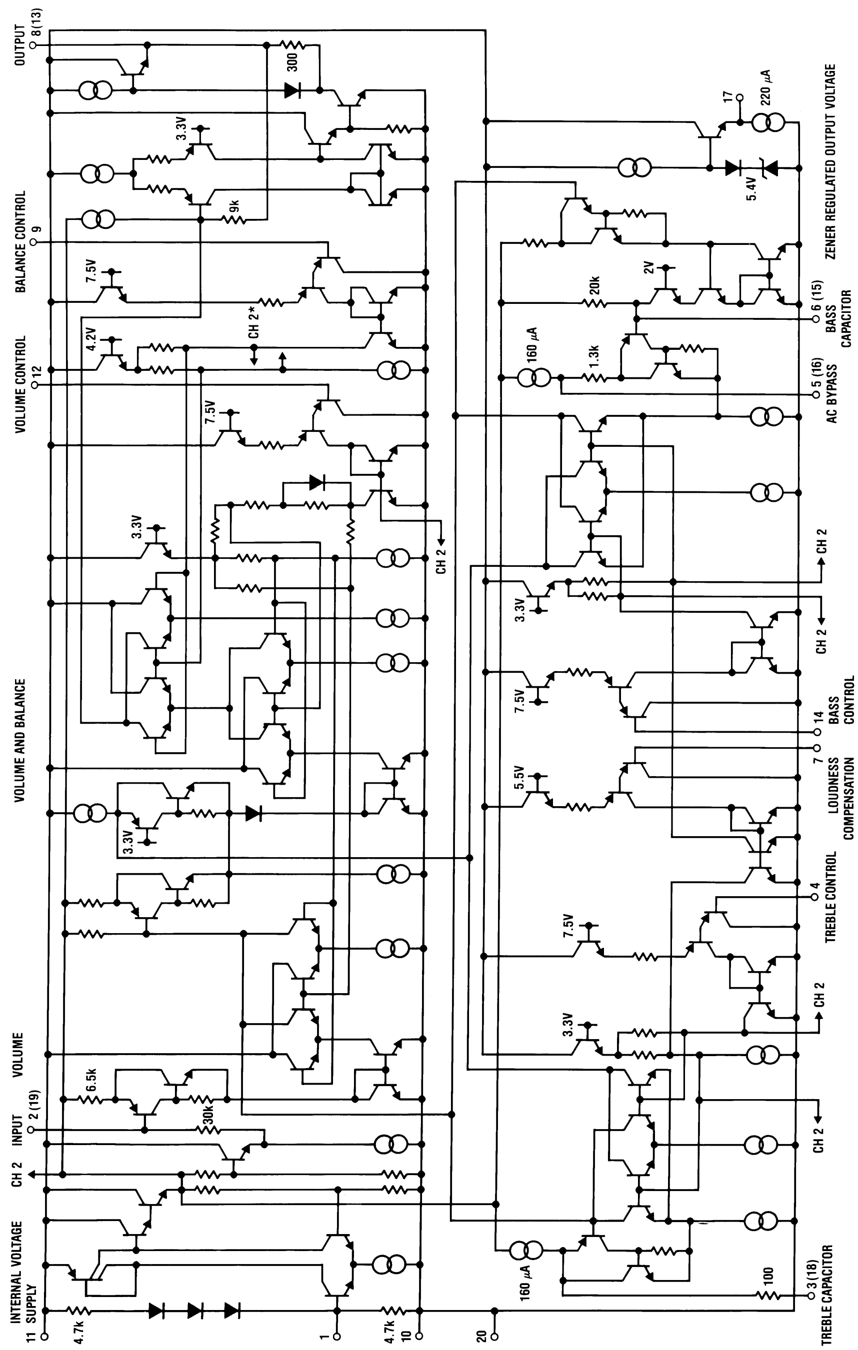


Figure 16. Tone Characteristic (Gain vs Frequency)

Simplified Schematic Diagram

(One Channel)



*Connections reversed

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM1036M/NOPB	ACTIVE	SOIC	DW	20	36	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	0 to 70	LM1036M	Samples
LM1036MX/NOPB	ACTIVE	SOIC	DW	20	1000	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	0 to 70	LM1036M	Samples
LM1036N/NOPB	ACTIVE	PDIP	NFH	20	18	Green (RoHS & no Sb/Br)	SN	Level-1-NA-UNLIM	0 to 70	LM1036N	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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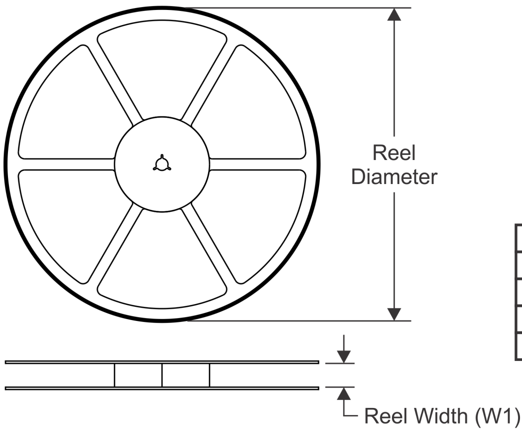
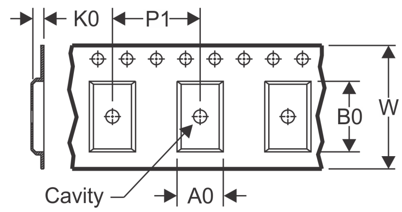
TAPE AND REEL INFORMATION

REEL DIMENSIONS

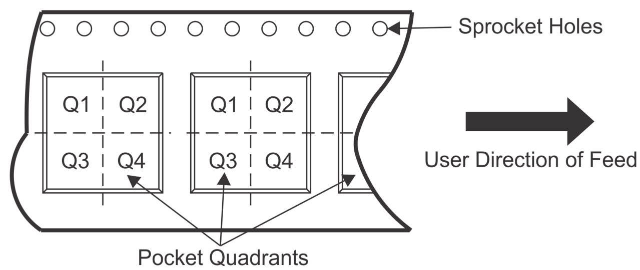


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

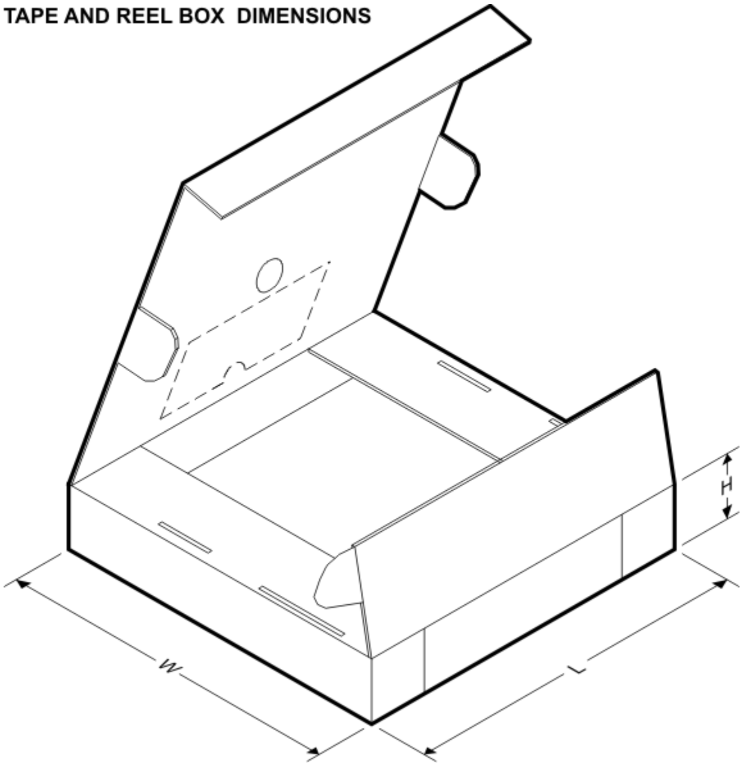
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM1036MX/NOPB	SOIC	DW	20	1000	330.0	24.4	10.9	13.3	3.25	12.0	24.0	Q1

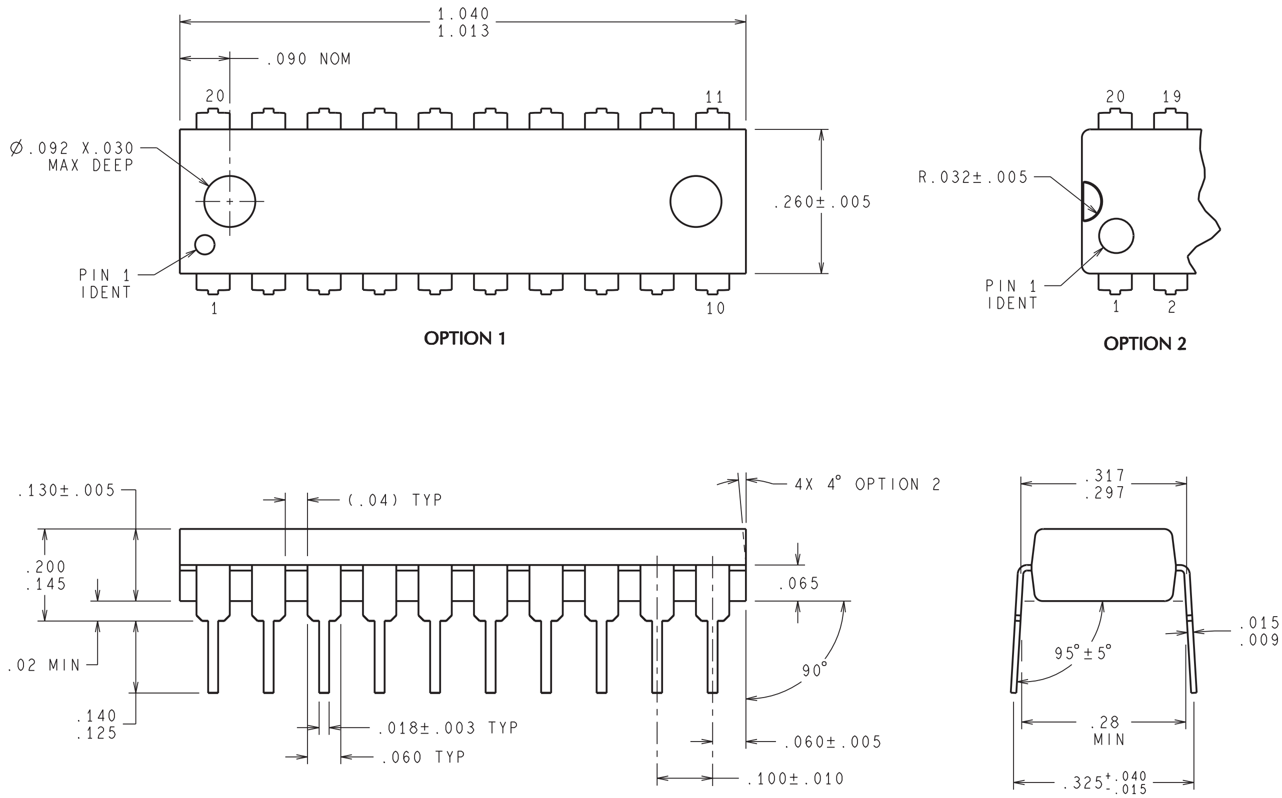
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

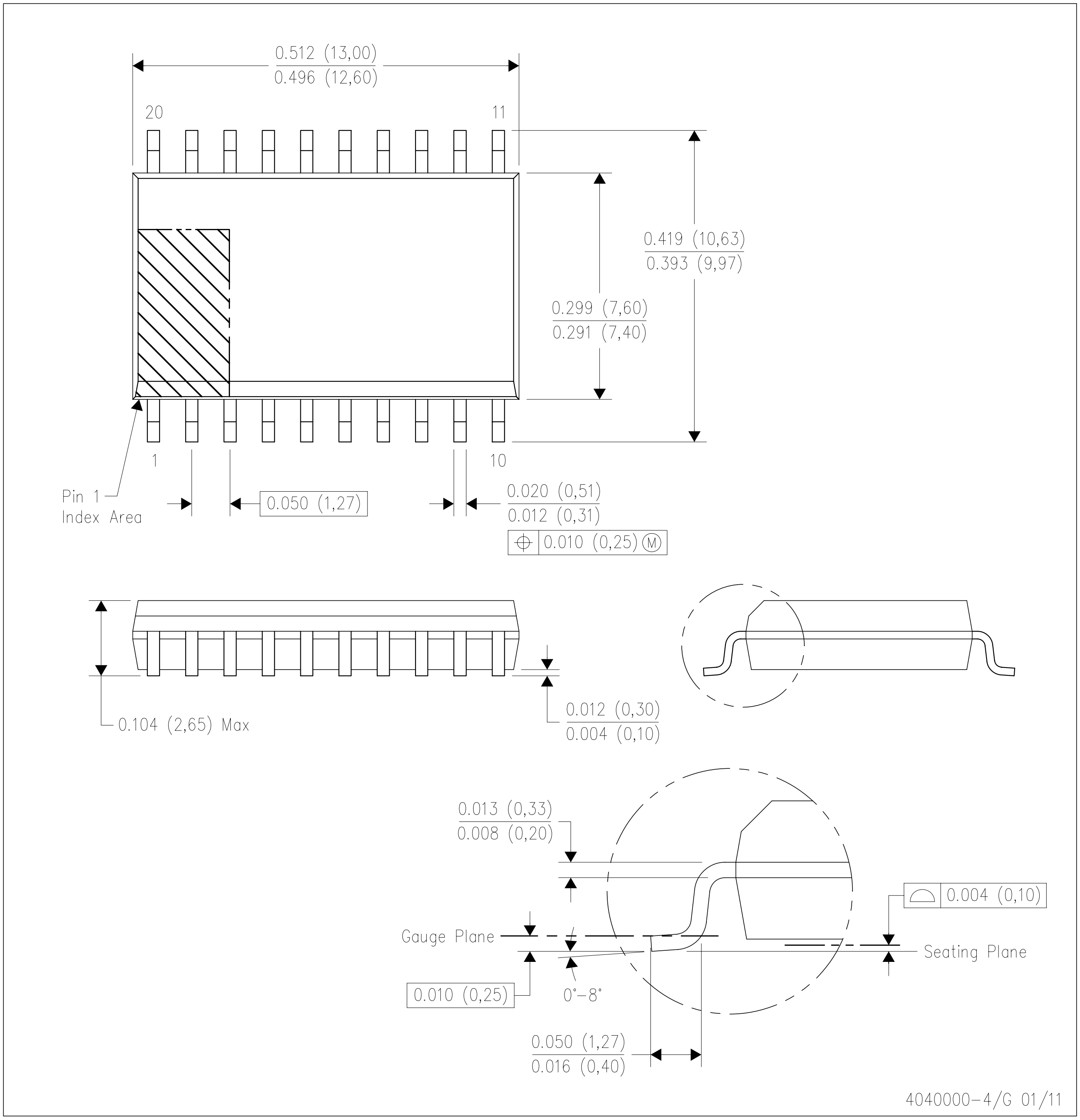
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM1036MX/NOPB	SOIC	DW	20	1000	358.0	343.0	63.0

NFH0020A



N20A (Rev G)

DW (R–PDSO–G20) PLASTIC SMALL OUTLINE



NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M–1994.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS–013 variation AC.

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